

FZ-1140-D9

- **Out line:** FZ-1140-D9 is a 40% glass fiber reinforced polyphenylene sulfide compound that is reduced flash and improved flow ability and mechanical properties for connector use.
- **Color:** Black and Natural (Light brown).

Engineering Properties of FZ-1140-D9

Properties	Test Method	Unit	FZ-1140-D9
General Information			
<ASTM>			GF40% High Flow & Low Flash
Physical			
Specific gravity	D-792	-	1.66
Water absorption, 23deg. /24Hrs. /in water	D-570	Wt. %	0.02
Mold shrinkage, MD /TD ^a	D-955	%	0.25/1.1
Mechanical			
Tensile strength	D-638	MPa	190
Tensile modulus	D-638	MPa	15000
Tensile elongation at break	D-638	%	1.8
Poisson's ratio	-	-	0.36
Flexural strength	D-790	MPa	270
Flexural modulus	D-790	MPa	13500
Flexural elongation at break	D-790	%	2.5
Izod impact strength notched / un notched	D-256	J/m	100/600
Compressive strength	D-695	MPa	200
Rockwell hardness, R/M	D-785	-	121/100
Coefficient of friction ^b , static /dynamic	-	-	0.35/0.35
Thermal			
Distortion temp. of under load, 1.82MPa	D-648	°C	265
Coefficient of thermal expansion, -30 to 90°C	D-696	m/mK	2.2x10 ⁻⁵
UL Flammability ^c	UL-94	-	V-0 ^e
Electrical			
Dielectric strength, t=1.6mm	D-149	kv/mm	16
Dielectric constant, 1MHz	D-150	-	4
Dissipation factor, 1MHz	D-150	-	0.002
Comparative tracking index (CTI)	D-3638	Volt	170
Arc resistance	D-495	sec.	125
Volume resistibility	D-257	Ohm.cm	10 ¹⁶
Process Conditions			
Cylinder temperature	-	°C	300-340
Mold temperature	-	°C	120-150

a: MD; Mold direction, TD; Transverse direction, b: P=150KPa, V=0.3m/s, PPS vs. carbon steel,
c: Average value of MD & TD, d: UL file No. E53829, e: t~0.4mm



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